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Connectivity	CANbus, I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	68
Program Memory Size	132KB (44K x 24)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (14x14)
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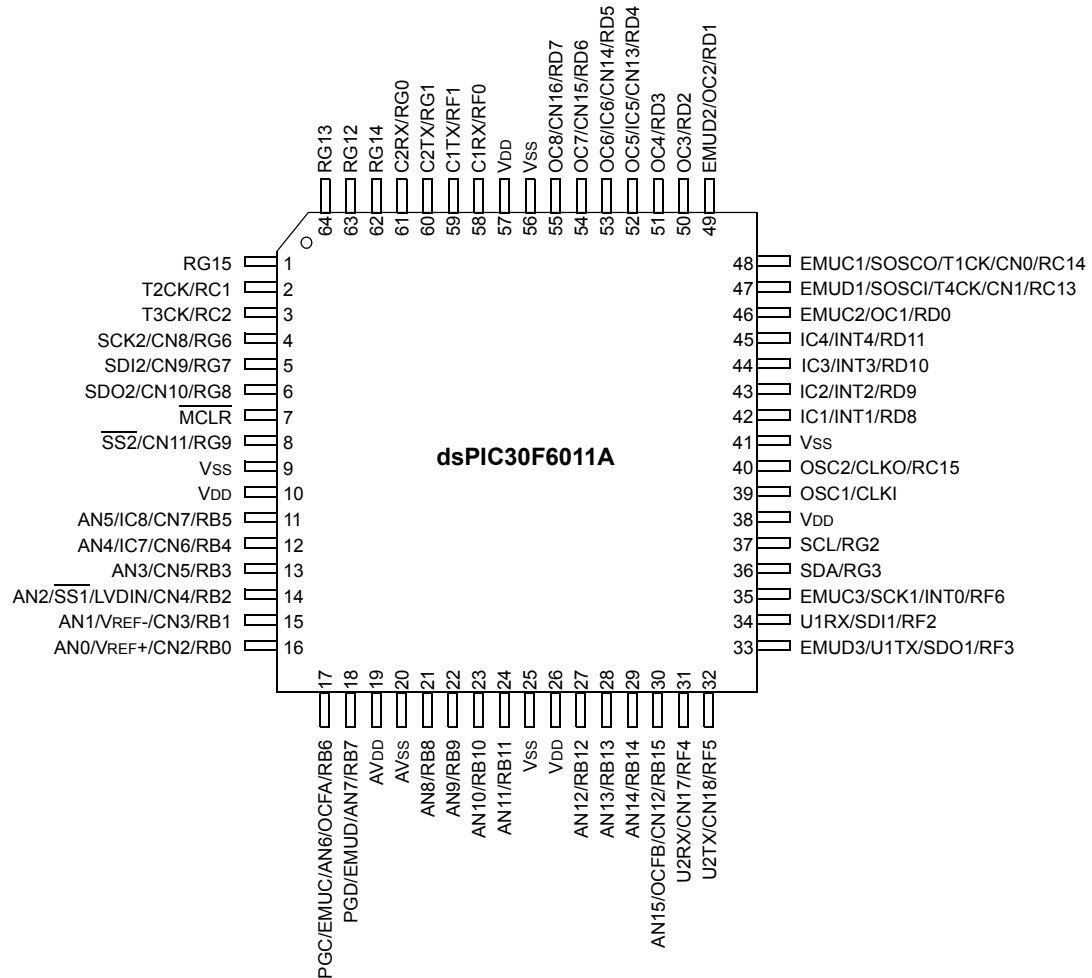
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dsPIC30F6011A/6012A/6013A/6014A

Pin Diagrams

64-Pin TQFP



dsPIC30F6011A/6012A/6013A/6014A

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All word accesses must be aligned to an even address. Misaligned word data fetches are not supported so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. Should a misaligned read or write be attempted, an address error trap will be generated. If the error occurred on a read, the instruction underway is completed, whereas if it occurred on a write, the instruction will be executed but the write will not occur. In either case, a trap will then be executed, allowing the system and/or user to examine the machine state prior to execution of the address fault.

FIGURE 3-10: DATA ALIGNMENT

	15	MSB	8	7	LSB	0	
0001	Byte1			Byte 0			0000
0003	Byte3			Byte 2			0002
0005	Byte5			Byte 4			0004

All byte loads into any W register are loaded into the LSB. The MSB is not modified.

A sign-extend (SE) instruction is provided to allow users to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, users can clear the MSB of any W register by executing a zero-extend (ZE) instruction on the appropriate address.

Although most instructions are capable of operating on word or byte data sizes, it should be noted that some instructions, including the DSP instructions, operate only on words.

3.2.5 NEAR DATA SPACE

An 8 Kbyte 'near' data space is reserved in X address memory space between 0x0000 and 0x1FFF, which is directly addressable via a 13-bit absolute address field within all memory direct instructions. The remaining X address space and all of the Y address space is addressable indirectly. Additionally, the whole of X data space is addressable using MOV instructions, which support memory direct addressing with a 16-bit address field.

3.2.6 SOFTWARE STACK

The dsPIC DSC devices contain a software stack. W15 is used as the Stack Pointer.

The Stack Pointer always points to the first available free word and grows from lower addresses towards higher addresses. It pre-decrements for stack pops and post-increments for stack pushes as shown in Figure 3-11. Note that for a PC push during any CALL instruction, the MSB of the PC is zero-extended before the push, ensuring that the MSB is always clear.

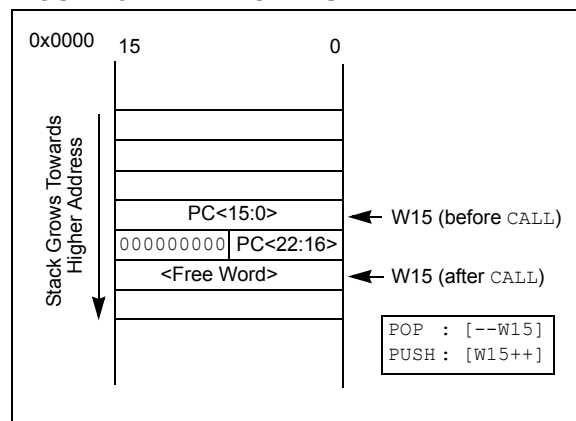
Note: A PC push during exception processing will concatenate the SRL register to the MSB of the PC prior to the push.

There is a Stack Pointer Limit register (SPLIM) associated with the Stack Pointer. SPLIM is uninitialized at Reset. As is the case for the Stack Pointer, SPLIM<0> is forced to '0' because all stack operations must be word aligned. Whenever an Effective Address (EA) is generated using W15 as a source or destination pointer, the address thus generated is compared with the value in SPLIM. If the contents of the Stack Pointer (W15) and the SPLIM register are equal and a push operation is performed, a Stack Error Trap will not occur. The Stack Error Trap will occur on a subsequent push operation. Thus, for example, if it is desirable to cause a Stack Error Trap when the stack grows beyond address 0x2000 in RAM, initialize the SPLIM with the value, 0x1FFE.

Similarly, a Stack Pointer underflow (stack error) trap is generated when the Stack Pointer address is found to be less than 0x0800, thus preventing the stack from interfering with the Special Function Register (SFR) space.

A write to the SPLIM register should not be immediately followed by an indirect read operation using W15.

FIGURE 3-11: CALL STACK FRAME



3.2.7 DATA RAM PROTECTION FEATURE

The dsPIC30F6011A/6012A/6013A/6014A devices support data RAM protection features which enable segments of RAM to be protected when used in conjunction with Boot and Secure Code Segment Security. BSRAM (Secure RAM segment for BS) is accessible only from the Boot Segment Flash code when enabled. SSRAM (Secure RAM segment for RAM) is accessible only from the Secure Segment Flash code when enabled.

See [Table 3-3](#) for an overview of the BSRAM and SSRAM SFRs.

dsPIC30F6011A/6012A/6013A/6014A

NOTES:

7.0 DATA EEPROM MEMORY

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the “dsPIC30F Family Reference Manual” (DS70046). For more information on the device instruction set and programming, refer to the “16-bit MCU and DSC Programmer’s Reference Manual” (DS70157).

The Data EEPROM Memory is readable and writable during normal operation over the entire VDD range. The data EEPROM memory is directly mapped in the program memory address space.

The four SFRs used to read and write the program Flash memory are used to access data EEPROM memory, as well. As described in [Section 6.5 “Control Registers”](#), these registers are:

- NVMCON
- NVMADR
- NVMADRU
- NVMKEY

The EEPROM data memory allows read and write of single words and 16-word blocks. When interfacing to data memory, NVMADR in conjunction with the NVMADRU register are used to address the EEPROM location being accessed. TBLRD and TBLWT instructions are used to read and write data EEPROM. The dsPIC30F devices have up to 8 Kbytes (4K words) of data EEPROM with an address range from 0x7FF000 to 0x7FFFFE.

A word write operation should be preceded by an erase of the corresponding memory location(s). The write typically requires 2 ms to complete but the write time will vary with voltage and temperature.

A program or erase operation on the data EEPROM does not stop the instruction flow. The user is responsible for waiting for the appropriate duration of time before initiating another data EEPROM write/erase operation. Attempting to read the data EEPROM while a programming or erase operation is in progress results in unspecified data.

Control bit WR initiates write operations similar to program Flash writes. This bit cannot be cleared, only set, in software. They are cleared in hardware at the completion of the write operation. The inability to clear the WR bit in software prevents the accidental or premature termination of a write operation.

The WREN bit, when set, will allow a write operation. On power-up, the WREN bit is clear. The WRERR bit is set when a write operation is interrupted by a MCLR Reset or a WDT Time-out Reset during normal operation. In these situations, following Reset, the user can check the WRERR bit and rewrite the location. The address register NVMADR remains unchanged.

Note: Interrupt flag bit NVMIF in the IFS0 register is set when write is complete. It must be cleared in software.

7.1 Reading the Data EEPROM

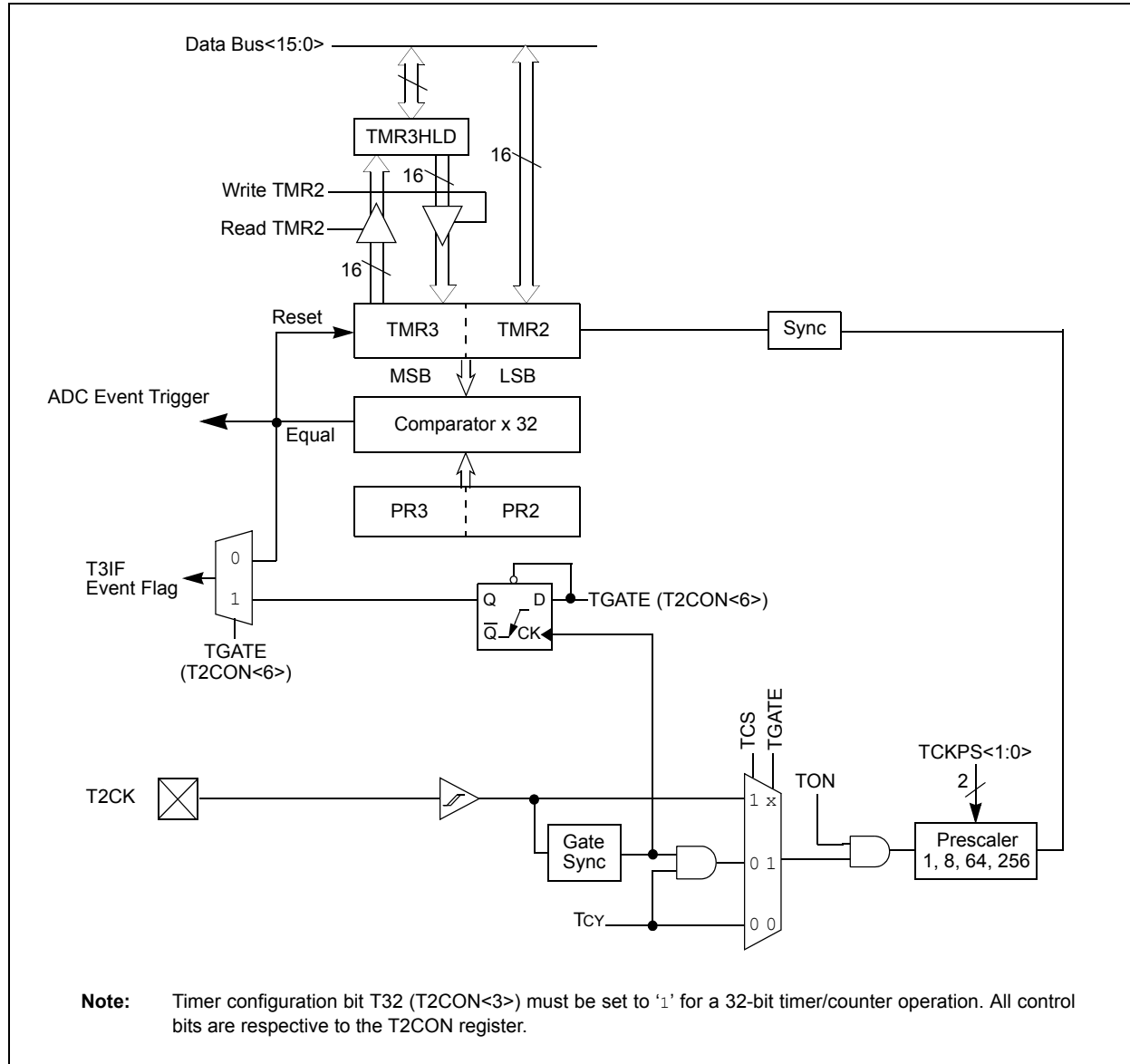
A TBLRD instruction reads a word at the current program word address. This example uses W0 as a pointer to data EEPROM. The result is placed in register W4 as shown in [Example 7-1](#).

EXAMPLE 7-1: DATA EEPROM READ

```
MOV    #LOW_ADDR_WORD,W0    ; Init Pointer
MOV    #HIGH_ADDR_WORD,W1
MOV    W1,TBLPAG
TBLRD  [ W0 ], W4            ; read data EEPROM
```


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FIGURE 10-1: 32-BIT TIMER2/3 BLOCK DIAGRAM



dsPIC30F6011A/6012A/6013A/6014A

10.1 Timer Gate Operation

The 32-bit timer can be placed in the Gated Time Accumulation mode. This mode allows the internal Tcy to increment the respective timer when the gate input signal (T2CK pin) is asserted high. Control bit TGATE (T2CON<6>) must be set to enable this mode. When in this mode, Timer2 is the originating clock source. The TGATE setting is ignored for Timer3. The timer must be enabled (TON = 1) and the timer clock source set to internal (TCS = 0).

The falling edge of the external signal terminates the count operation but does not reset the timer. The user must reset the timer in order to start counting from zero.

10.2 ADC Event Trigger

When a match occurs between the 32-bit timer (TMR3/TMR2) and the 32-bit combined period register (PR3/PR2), or between the 16-bit timer TMR3 and the 16-bit period register PR3, a special ADC trigger event signal is generated by Timer3.

10.3 Timer Prescaler

The input clock (FOSC/4 or external clock) to the timer has a prescale option of 1:1, 1:8, 1:64 and 1:256, selected by control bits TCKPS<1:0> (T2CON<5:4> and T3CON<5:4>). For the 32-bit timer operation, the originating clock source is Timer2. The prescaler operation for Timer3 is not applicable in this mode. The prescaler counter is cleared when any of the following occurs:

- A write to the TMR2/TMR3 register
- A write to the T2CON/T3CON register
- A device Reset, such as a POR and BOR

However, if the timer is disabled (TON = 0), then the Timer 2 prescaler cannot be reset since the prescaler clock is halted.

TMR2/TMR3 is not cleared when T2CON/T3CON is written.

10.4 Timer Operation During Sleep Mode

During CPU Sleep mode, the timer will not operate because the internal clocks are disabled.

10.5 Timer Interrupt

The 32-bit timer module can generate an interrupt on period match or on the falling edge of the external gate signal. When the 32-bit timer count matches the respective 32-bit period register, or the falling edge of the external “gate” signal is detected, the T3IF bit (IFS0<7>) is asserted and an interrupt will be generated if enabled. In this mode, the T3IF interrupt flag is used as the source of the interrupt. The T3IF bit must be cleared in software.

Enabling an interrupt is accomplished via the respective timer interrupt enable bit, T3IE (IEC0<7>).

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12.1.2 CAPTURE BUFFER OPERATION

Each capture channel has an associated FIFO buffer which is four 16-bit words deep. There are two status flags which provide status on the FIFO buffer:

- ICBFNE – Input Capture Buffer Not Empty
- ICOV – Input Capture Overflow

The ICBFNE will be set on the first input capture event and remain set until all capture events have been read from the FIFO. As each word is read from the FIFO, the remaining words are advanced by one position within the buffer.

In the event that the FIFO is full with four capture events and a fifth capture event occurs prior to a read of the FIFO, an overflow condition will occur and the ICOV bit will be set to a logic '1'. The fifth capture event is lost and is not stored in the FIFO. No additional events will be captured until all four events have been read from the buffer.

If a FIFO read is performed after the last read and no new capture event has been received, the read will yield indeterminate results.

12.1.3 TIMER2 AND TIMER3 SELECTION MODE

The input capture module consists of up to 8 input capture channels. Each channel can select between one of two timers for the time base, Timer2 or Timer3.

Selection of the timer resource is accomplished through SFR bit, ICTMR (ICxCON<7>). Timer3 is the default timer resource available for the input capture module.

12.1.4 HALL SENSOR MODE

When the input capture module is set for capture on every edge, rising and falling, ICM<2:0> = 001, the following operations are performed by the input capture logic:

- The input capture interrupt flag is set on every edge, rising and falling.
- The interrupt on Capture mode setting bits, ICI<1:0>, is ignored since every capture generates an interrupt.
- A capture overflow condition is not generated in this mode.

12.2 Input Capture Operation During Sleep and Idle Modes

An input capture event will generate a device wake-up or interrupt, if enabled, if the device is in CPU Idle or Sleep mode.

Independent of the timer being enabled, the input capture module will wake-up from the CPU Sleep or Idle mode when a capture event occurs if ICM<2:0> = 111 and the interrupt enable bit is asserted. The same wake-up can generate an interrupt if the conditions for processing the interrupt have been satisfied. The wake-up feature is useful as a method of adding extra external pin interrupts.

12.2.1 INPUT CAPTURE IN CPU SLEEP MODE

CPU Sleep mode allows input capture module operation with reduced functionality. In the CPU Sleep mode, the ICI<1:0> bits are not applicable and the input capture module can only function as an external interrupt source.

The capture module must be configured for interrupt only on rising edge (ICM<2:0> = 111) in order for the input capture module to be used while the device is in Sleep mode. The prescale settings of 4:1 or 16:1 are not applicable in this mode.

12.2.2 INPUT CAPTURE IN CPU IDLE MODE

CPU Idle mode allows input capture module operation with full functionality. In the CPU Idle mode, the Interrupt mode selected by the ICI<1:0> bits is applicable, as well as the 4:1 and 16:1 capture prescale settings which are defined by control bits ICM<2:0>. This mode requires the selected timer to be enabled. Moreover, the ICSIDL bit must be asserted to a logic '0'.

If the input capture module is defined as ICM<2:0> = 111 in CPU Idle mode, the input capture pin will serve only as an external interrupt pin.

12.3 Input Capture Interrupts

The input capture channels have the ability to generate an interrupt based upon the selected number of capture events. The selection number is set by control bits ICI<1:0> (ICxCON<6:5>).

Each channel provides an interrupt flag (ICxIF) bit. The respective capture channel interrupt flag is located in the corresponding IFSx status register.

Enabling an interrupt is accomplished via the respective capture channel interrupt enable (ICxIE) bit. The capture interrupt enable bit is located in the corresponding IEC control register.

TABLE 17-1: CAN1 REGISTER MAP⁽¹⁾

SFR Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
C1RXF0SID	0300	—	—	—	—	—	Receive Acceptance Filter 0 Standard Identifier <10:0>											EXIDE
C1RXF0EIDL	0302	—	—	—	—	—	Receive Acceptance Filter 0 Extended Identifier <17:6>											0000 uuuu uuuu uuuu
C1RXF0EIDL	0304	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uu00 0000 0000
C1RXF1SID	0308	—	—	—	—	—	Receive Acceptance Filter 1 Standard Identifier <10:0>											EXIDE
C1RXF1EIDL	030A	—	—	—	—	—	Receive Acceptance Filter 1 Extended Identifier <17:6>											0000 uuuu uuuu uuuu
C1RXF1EIDL	030C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uu00 0000 0000
C1RXF2SID	0310	—	—	—	—	—	Receive Acceptance Filter 2 Standard Identifier <10:0>											EXIDE
C1RXF2EIDL	0312	—	—	—	—	—	Receive Acceptance Filter 2 Extended Identifier <17:6>											0000 uuuu uuuu uuuu
C1RXF2EIDL	0314	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uu00 0000 0000
C1RXF3SID	0318	—	—	—	—	—	Receive Acceptance Filter 3 Standard Identifier <10:0>											EXIDE
C1RXF3EIDL	031A	—	—	—	—	—	Receive Acceptance Filter 3 Extended Identifier <17:6>											0000 uuuu uuuu uuuu
C1RXF3EIDL	031C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uu00 0000 0000
C1RXF4SID	0320	—	—	—	—	—	Receive Acceptance Filter 4 Standard Identifier <10:0>											EXIDE
C1RXF4EIDL	0322	—	—	—	—	—	Receive Acceptance Filter 4 Extended Identifier <17:6>											0000 uuuu uuuu uuuu
C1RXF4EIDL	0324	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uu00 0000 0000
C1RXF5SID	0328	—	—	—	—	—	Receive Acceptance Filter 5 Standard Identifier <10:0>											EXIDE
C1RXF5EIDL	032A	—	—	—	—	—	Receive Acceptance Filter 5 Extended Identifier <17:6>											0000 uuuu uuuu uuuu
C1RXF5EIDL	032C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uu00 0000 0000
C1RXMOSID	0330	—	—	—	—	—	Receive Acceptance Mask 0 Standard Identifier <10:0>											MIDE
C1RXMOEIDL	0332	—	—	—	—	—	Receive Acceptance Mask 0 Extended Identifier <17:6>											0000 uuuu uuuu uuuu
C1RXMOEIDL	0334	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uu00 0000 0000
C1RXM1SID	0338	—	—	—	—	—	Receive Acceptance Mask 1 Standard Identifier <10:0>											MIDE
C1RXM1EIDL	033A	—	—	—	—	—	Receive Acceptance Mask 1 Extended Identifier <17:6>											0000 uuuu uuuu uuuu
C1RXM1EIDL	033C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uu00 0000 0000
C1TX2SID	0340	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uu00 0000 0000
C1TX2EIDL	0342	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	TXIDE
C1TX2DLC	0344	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu 0000 uuuu uuuu
C1TX2B1	0346	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uuuu uuuu u000
C1TX2B2	0348	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uuuu uuuu uuuu
C1TX2B3	034A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uuuu uuuu uuuu
C1TX2B4	034C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uuuu uuuu uuuu
C1TX2CON	034E	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu uuuu uuuu uuuu
C1TX1SID	0350	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
C1TX1EIDL	0352	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu u000 uuuu uuuu
C1TX1DLC	0354	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	uuuu 0000 uuuu uuuu

Legend: u = uninitialized bit; — = unimplemented bit, read as '0'

Note 1: Refer to the "dsPIC30F Family Reference Manual" (DS70046) for descriptions of register bit fields.

TABLE 17-2: CAN2 REGISTER MAP⁽¹⁾ (CONTINUED)

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
C2TX1B1	0416																	Transmit Buffer 1 Byte 0
C2TX1B2	0418																	Transmit Buffer 1 Byte 2
C2TX1B3	041A																	Transmit Buffer 1 Byte 4
C2TX1B4	041C																	Transmit Buffer 1 Byte 6
C2TX1CON	041E	—	—	—	—	—	—	—	—	—	TXABT	TXLARB	TXERR	TXREQ	—	—	TXPRI<1:0>	0000 0000 0000 0000
C2TX0SID	0420																	Transmit Buffer 0 Standard Identifier <5:0>
C2TX0EID	0422																	SRR TXIDE
C2TX0DLC	0424																	Transmit Buffer 0 Extended Identifier <13:6>
C2TX0B1	0426																	DLC<3:0>
C2TX0B2	0428																	Transmit Buffer 0 Byte 0
C2TX0B3	042A																	Transmit Buffer 0 Byte 2
C2TX0B4	042C																	Transmit Buffer 0 Byte 4
C2TX0CON	042E	—	—	—	—	—	—	—	—	—	—	TXABT	TXLARB	TXERR	TXREQ	—	—	Transmit Buffer 0 Byte 6
C2RX1SID	0430	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	TXPRI<1:0>
C2RX1EID	0432	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SRR RXIDE
C2RX1DLC	0434																	0000 0000 0000 0000
C2RX1B1	0436																	0000 0000 0000 0000
C2RX1B2	0438																	0000 0000 0000 0000
C2RX1B3	043A																	0000 0000 0000 0000
C2RX1B4	043C																	0000 0000 0000 0000
C2RX1CON	043E	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
C2RX0SID	0440	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
C2RX0EID	0442	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
C2RX0DLC	0444																	0000 0000 0000 0000
C2RX0B1	0446																	0000 0000 0000 0000
C2RX0B2	0448																	0000 0000 0000 0000
C2RX0B3	044A																	0000 0000 0000 0000
C2RX0B4	044C																	0000 0000 0000 0000
C2RX0CON	044E	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
C2CTRL	0450	CANCAP	—	CSIDLE	ABAT	CANCKS	REQOP<2:0>	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
C2CFG1	0452	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
C2CFG2	0454	—	WAKFIL	—	—	—	SEG2PH<2:0>	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
C2INTF	0456	RX0OVR	RX1OVR	TXBO	TXEP	RXEP	TXWAR	RXWAR	EWARN	IVRIF	WAKIF	ERRIF	TX2IF	TX1IF	TX0IF	RX1IF	RX0IF	0000 0000 0000 0000
C2INTE	0458	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
C2EC	045A																	0000 0000 0000 0000

Legend: u = uninitialized bit; — = unimplemented bit, read as '0'

Note 1: Refer to the "dsPIC30F Family Reference Manual" (DS70046) for descriptions of register bit fields.

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TABLE 20-7: SYSTEM INTEGRATION REGISTER MAP FOR dsPIC30F601XA⁽¹⁾

SFR Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
RCON	0740	TRAPR	IOPUWR	BGST	LVDEN					EXTR	SWR	LOCK	WDTO	SLEEP	IDLE	BOR	POR	Depends on type of Reset.
OSCCON	0742	—	—	—	—	—	—	—	—	POST<1:0>	—	—	—	CF	—	LPOSCEN	OSWEN	Depends on Configuration bits.
OSCTUN	0744	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
PMD1	0770	T5MD	T4MD	T3MD	T2MD	T1MD	—	—	DC1MD	I2CMD	U2MD	U1MD	SP2MD	SP1MD	C2MD	C1MD	ADCMD	0000 0000 0000 0000
PMD2	0772	IC8MD	IC7MD	IC6MD	IC5MD	IC4MD	IC3MD	IC2MD	IC1MD	OC8MD	OC7MD	OC6MD	OC5MD	OC4MD	OC3MD	OC2MD	OC1MD	0000 0000 0000 0000

Legend: — = unimplemented bit, read as '0'

Note 1: Refer to the "dsPIC30F Family Reference Manual" (DS70046) for descriptions of register bit fields.

TABLE 20-8: DEVICE CONFIGURATION REGISTER MAP⁽¹⁾

Name	Address	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FOSC	F80000	FOKSM<1:0>	—	—	—	—	—	FOS<2:0>	—	—	—	—	—	—	—	—	—
FWD	F80002	FWDTEN	—	—	—	—	—	—	—	—	—	FWPSA<1:0>	—	—	FWPSB<3:0>	—	—
FBORPOR	F80004	MCLREN	—	—	—	—	PWMPIN ⁽²⁾	HPOL ⁽²⁾	LPOL ⁽²⁾	BOREN	—	BORV<1:0>	—	—	—	FPWRT<1:0>	—
FBS	F80006	—	—	—	RBS<1:0>	—	—	—	EBS	—	—	—	—	—	BSS<2:0>	—	BWRP
FSS	F80008	—	—	—	RSS<1:0>	—	—	—	ESS<1:0>	—	—	—	—	—	SSS<2:0>	—	SWRP
FGS	F8000A	—	—	—	—	—	—	—	—	—	—	—	—	—	GSS<1:0>	—	GWRP
FICD	F8000C	BKBUG	COE	—	—	—	—	—	—	—	—	—	—	—	—	—	ICS<1:0>

Legend: — = unimplemented bit, read as '0'

Note 1: Refer to the "dsPIC30F Family Reference Manual" (DS70046) for descriptions of register bit fields.

Note 2: These bits are reserved (read as '1' and must be programmed as '1').

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TABLE 21-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
9	BTG	BTG $f, \#bit4$	Bit Toggle f	1	1	None
		BTG $Ws, \#bit4$	Bit Toggle Ws	1	1	None
10	BTSC	BTSC $f, \#bit4$	Bit Test f , Skip if Clear	1	1 (2 or 3)	None
		BTSC $Ws, \#bit4$	Bit Test Ws , Skip if Clear	1	1 (2 or 3)	None
11	BTSS	BTSS $f, \#bit4$	Bit Test f , Skip if Set	1	1 (2 or 3)	None
		BTSS $Ws, \#bit4$	Bit Test Ws , Skip if Set	1	1 (2 or 3)	None
12	BTST	BTST $f, \#bit4$	Bit Test f	1	1	Z
		BTST.C $Ws, \#bit4$	Bit Test Ws to C	1	1	C
		BTST.Z $Ws, \#bit4$	Bit Test Ws to Z	1	1	Z
		BTST.C Ws, Wb	Bit Test $Ws < Wb >$ to C	1	1	C
		BTST.Z Ws, Wb	Bit Test $Ws < Wb >$ to Z	1	1	Z
13	BTSTS	BTSTS $f, \#bit4$	Bit Test then Set f	1	1	Z
		BTSTS.C $Ws, \#bit4$	Bit Test Ws to C, then Set	1	1	C
		BTSTS.Z $Ws, \#bit4$	Bit Test Ws to Z, then Set	1	1	Z
14	CALL	CALL $lit23$	Call subroutine	2	2	None
		CALL Wn	Call indirect subroutine	1	2	None
15	CLR	CLR f	$f = 0x0000$	1	1	None
		CLR $WREG$	$WREG = 0x0000$	1	1	None
		CLR Ws	$Ws = 0x0000$	1	1	None
		CLR $Acc, Wx, Wxd, Wy, Wyd, AWB$	Clear Accumulator	1	1	OA,OB,SA,SB
16	CLRWDT	CLRWDT	Clear Watchdog Timer	1	1	WDTO,Sleep
17	COM	COM f	$f = \bar{f}$	1	1	N,Z
		COM $f, WREG$	$WREG = \bar{f}$	1	1	N,Z
		COM Ws, Wd	$Wd = \overline{Ws}$	1	1	N,Z
18	CP	CP f	Compare f with $WREG$	1	1	C,DC,N,OV,Z
		CP $Wb, \#lit5$	Compare Wb with $lit5$	1	1	C,DC,N,OV,Z
		CP Wb, Ws	Compare Wb with Ws ($Wb - Ws$)	1	1	C,DC,N,OV,Z
19	CP0	CP0 f	Compare f with $0x0000$	1	1	C,DC,N,OV,Z
		CP0 Ws	Compare Ws with $0x0000$	1	1	C,DC,N,OV,Z
20	CPB	CPB f	Compare f with $WREG$, with Borrow	1	1	C,DC,N,OV,Z
		CPB $Wb, \#lit5$	Compare Wb with $lit5$, with Borrow	1	1	C,DC,N,OV,Z
		CPB Wb, Ws	Compare Wb with Ws , with Borrow ($Wb - Ws - C$)	1	1	C,DC,N,OV,Z
21	CPSEQ	CPSEQ Wb, Wn	Compare Wb with Wn , skip if =	1	1 (2 or 3)	None
22	CPSGT	CPSGT Wb, Wn	Compare Wb with Wn , skip if >	1	1 (2 or 3)	None
23	CPSLT	CPSLT Wb, Wn	Compare Wb with Wn , skip if <	1	1 (2 or 3)	None
24	CPSNE	CPSNE Wb, Wn	Compare Wb with Wn , skip if \neq	1	1 (2 or 3)	None
25	DAW	DAW Wn	$Wn =$ decimal adjust Wn	1	1	C
26	DEC	DEC f	$f = f - 1$	1	1	C,DC,N,OV,Z
		DEC $f, WREG$	$WREG = f - 1$	1	1	C,DC,N,OV,Z
		DEC Ws, Wd	$Wd = Ws - 1$	1	1	C,DC,N,OV,Z
27	DEC2	DEC2 f	$f = f - 2$	1	1	C,DC,N,OV,Z
		DEC2 $f, WREG$	$WREG = f - 2$	1	1	C,DC,N,OV,Z
		DEC2 Ws, Wd	$Wd = Ws - 2$	1	1	C,DC,N,OV,Z
28	DISI	DISI $\#lit14$	Disable Interrupts for k instruction cycles	1	1	None

22.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

22.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

22.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

22.10 PICkit 3 In-Circuit Debugger/Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

dsPIC30F6011A/6012A/6013A/6014A

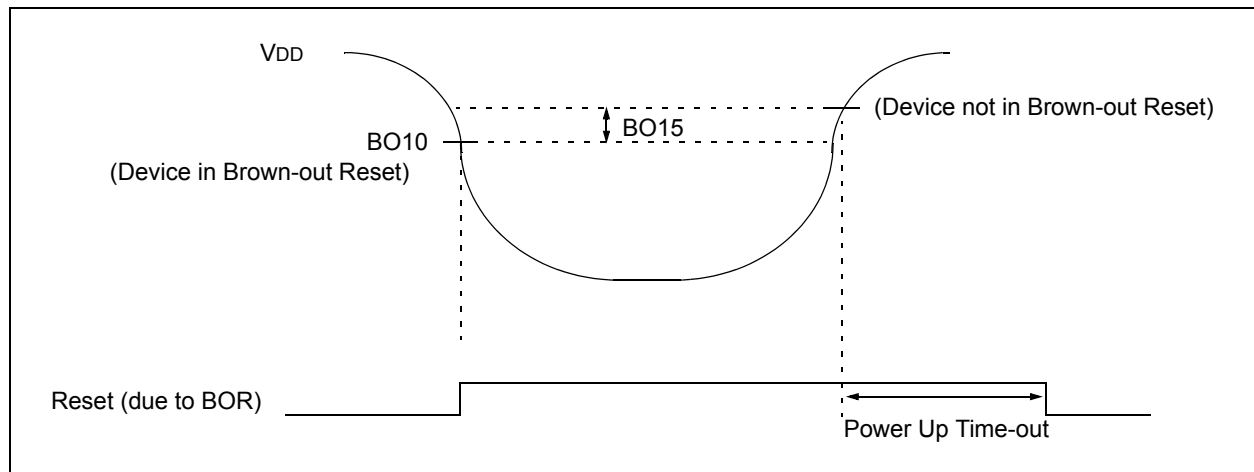
TABLE 23-10: ELECTRICAL CHARACTERISTICS: LVDL

DC CHARACTERISTICS				Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾		Min	Typ	Max	Units	Conditions
LV10	VPLVD	LVDL Voltage on VDD transition high to low	LVDL = 0000 ⁽²⁾	—	—	—	V	
			LVDL = 0001 ⁽²⁾	—	—	—	V	
			LVDL = 0010 ⁽²⁾	—	—	—	V	
			LVDL = 0011 ⁽²⁾	—	—	—	V	
			LVDL = 0100	2.50	—	2.65	V	
			LVDL = 0101	2.70	—	2.86	V	
			LVDL = 0110	2.80	—	2.97	V	
			LVDL = 0111	3.00	—	3.18	V	
			LVDL = 1000	3.30	—	3.50	V	
			LVDL = 1001	3.50	—	3.71	V	
			LVDL = 1010	3.60	—	3.82	V	
			LVDL = 1011	3.80	—	4.03	V	
			LVDL = 1100	4.00	—	4.24	V	
			LVDL = 1101	4.20	—	4.45	V	
			LVDL = 1110	4.50	—	4.77	V	
LV15	VLVDIN	External LVD input pin threshold voltage	LVDL = 1111	—	—	—	V	

Note 1: These parameters are characterized but not tested in manufacturing.

Note 2: These values not in usable operating range.

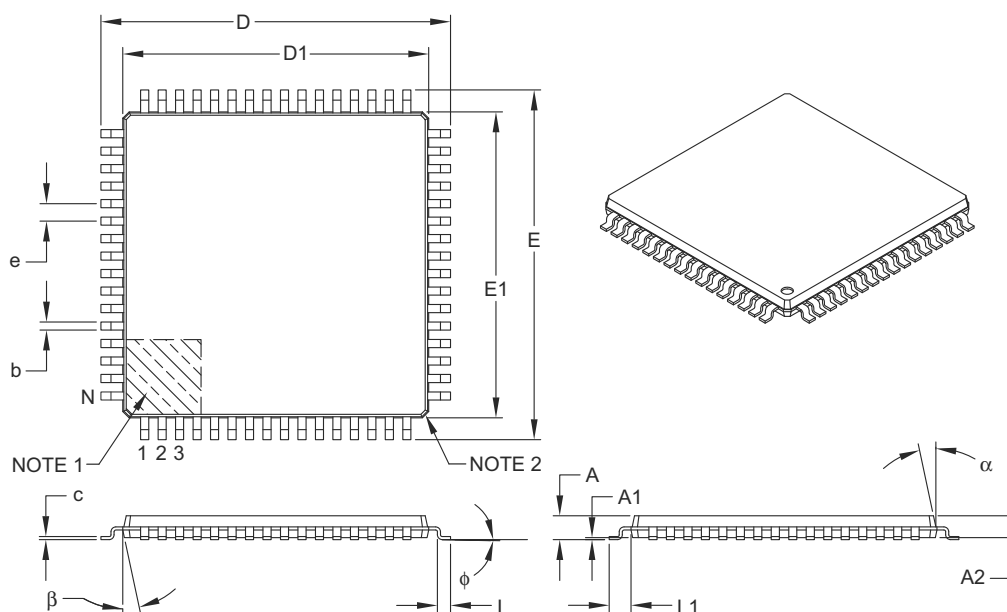
FIGURE 23-2: BROWN-OUT RESET CHARACTERISTICS



dsPIC30F6011A/6012A/6013A/6014A

64-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	64		
Lead Pitch	e	0.80 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	16.00 BSC		
Overall Length	D	16.00 BSC		
Molded Package Width	E1	14.00 BSC		
Molded Package Length	D1	14.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

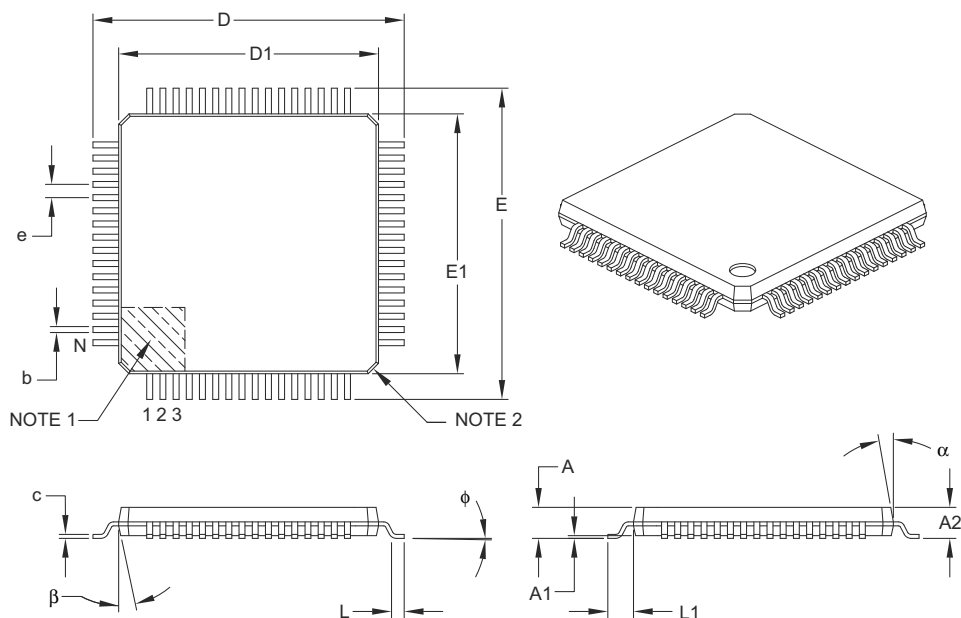
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-066B

dsPIC30F6011A/6012A/6013A/6014A

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Leads	N		64		
Lead Pitch	e		0.50 BSC		
Overall Height	A		–	–	1.20
Molded Package Thickness	A2		0.95	1.00	1.05
Standoff	A1		0.05	–	0.15
Foot Length	L		0.45	0.60	0.75
Footprint	L1		1.00 REF		
Foot Angle	phi		0°	3.5°	7°
Overall Width	E		12.00 BSC		
Overall Length	D		12.00 BSC		
Molded Package Width	E1		10.00 BSC		
Molded Package Length	D1		10.00 BSC		
Lead Thickness	c		0.09	–	0.20
Lead Width	b		0.17	0.22	0.27
Mold Draft Angle Top	alpha		11°	12°	13°
Mold Draft Angle Bottom	beta		11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

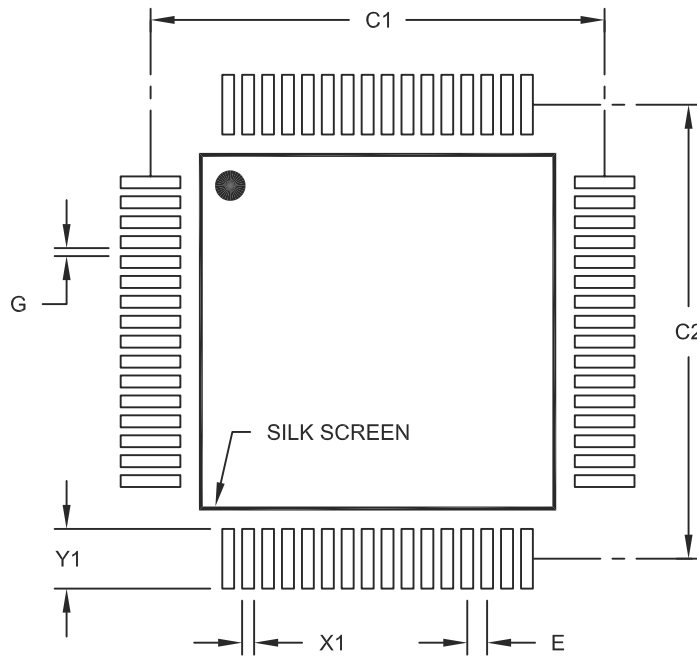
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

dsPIC30F6011A/6012A/6013A/6014A

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packages>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085A

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